## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Jen-Yi Chen	10/23/2008
Chin-Horng Wang	10/23/2008

#### **RECEIVING PARTY DATA**

Name:	Industrial Technology Research Institute	
Street Address:	No. 195, Sec. 4, Chung Hsing Rd., Chutung	
City:	Hsinchu	
State/Country:	TAIWAN	
Postal Code:	31040	

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12348322

## **CORRESPONDENCE DATA**

Fax Number: (949)660-0809

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

usa@jcipgroup.com.tw

Correspondent Name: JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE

Address Line 1: 7F.-1, NO.100, ROOSEVELT RD., SEC. 2

Taipei, TAIWAN 100 Address Line 4:

ATTORNEY DOCKET NUMBER: 28443-US-PA

NAME OF SUBMITTER: Belinda Lee

Total Attachments: 2

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**PATENT** 

**REEL: 022085 FRAME: 0831** 



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### ASSIGNMENT

WHEREAS.

1. Chen, Jen-Yi

2. Wang, Chin-Horng

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: MEMS STRUCTURE AND METHOD OF MANUFACTURING THE SAME

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute
of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said Invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

# ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Date: Oct. 23, 2008

Sole or First Joint Inventor: Chen, Jen-Yi

**RECORDED: 01/10/2009** 

Signature: <u>(him-)for ng () ang</u> Date: <u>Oct. >3 > nof</u>
Second Joint Inventor (if any). Wang, Chin/Horng